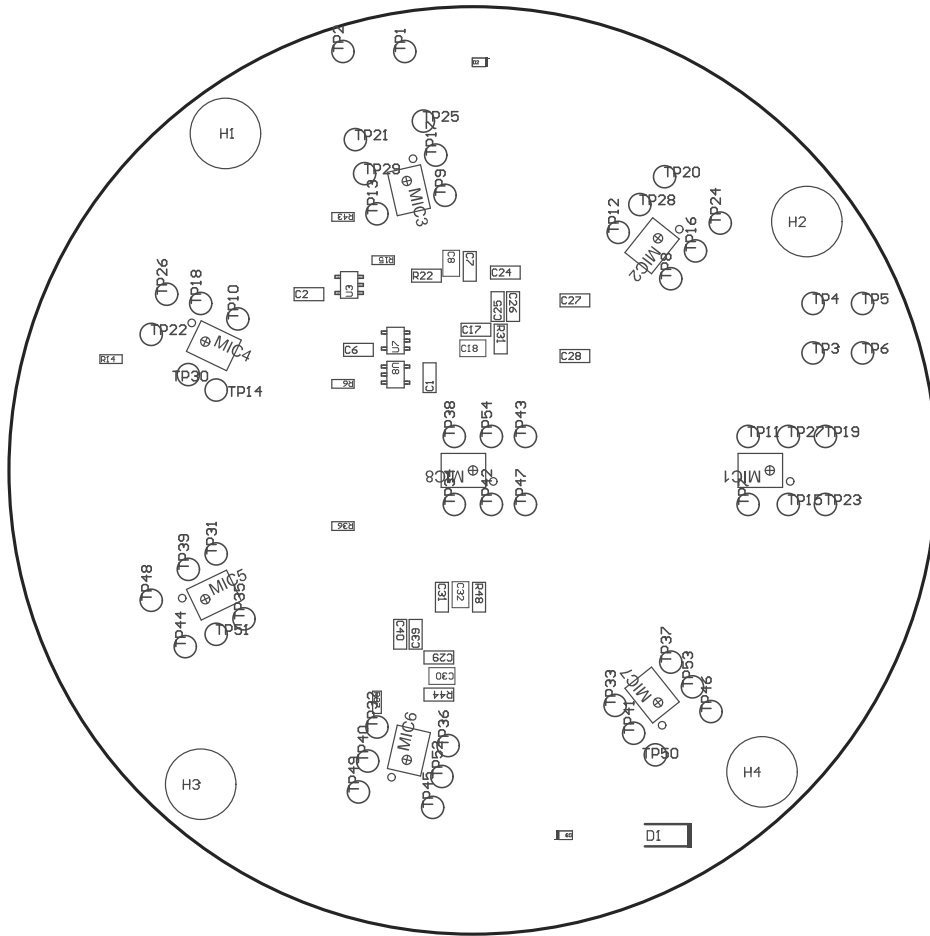
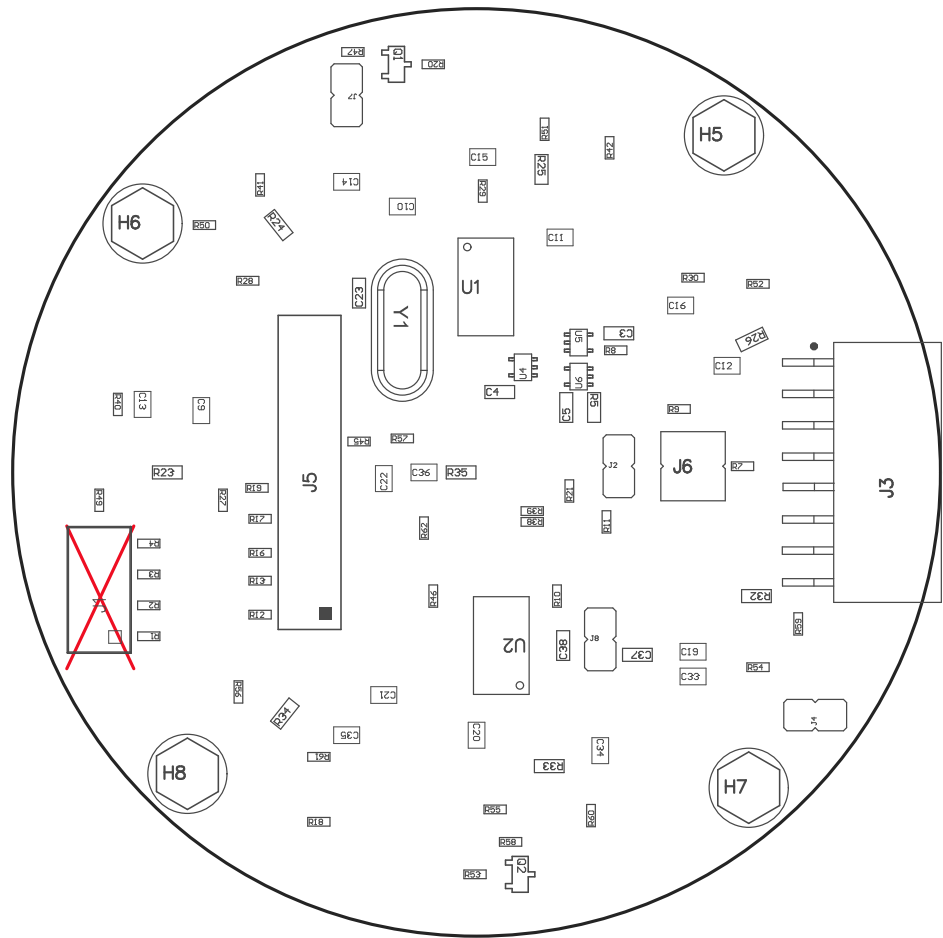


- ZZ1 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ2 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01454	REV: B	SVN REV: Not In VersionControl
PLOT NAME = Top Assembly Drawing	GENERATED : 4/17/2017 5:09:33 PM		TEXAS INSTRUMENTS



PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01454	REV: B	SVN REV: Not In VersionControl
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/17/2017 5:09:34 PM		TEXAS INSTRUMENTS

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